## B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

- 1. (Currently Amended) A fabrication method of a mold for a microlens having a desired radius (R) of curvature, said the method comprising the steps of:
- (a) preparing a substrate at least a portion of which is electrically conductive;
- (b) forming an insulating mask layer on the conductive portion of the substrate such that the insulating mask layer has an opening to expose the conductive portion of the substrate, a diameter or width  $(\phi)$  of the opening being  $10\mu\text{m} \le \phi \le 0.35R$  and  $R \le 200\mu\text{m}$ ;
- (c) forming an opening in the mask layer to expose the conductive portion of the substrate at the opening such that a diameter or width  $(\phi)$  of the opening is  $10\mu\text{m} \le \phi \le 0.35\text{R}$  and  $R \le 200\mu\text{m}$ ;
- (d) performing electroplating to form the mold with the desired radius (R) of eurvature using the conductive portion of the substrate as a cathode to deposit a plated layer portion in the opening and on the mask layer; and
- - (e) forming a sacrificial layer on the plated portion;
  - (f) forming an electrode layer on the sacrificial layer; and

(g) forming a plated portion used as the mold on the electrode layer by electroplating by using the electrode layer as a cathode,

wherein the desired radius (R) of curvature and the minimum radius  $(R_{min})$  are radii at an optical axis of the plated portion.

## 2-6. (Cancelled)

- 7. (Currently Amended) The method according to claim 1, wherein said-the step (d)(c) comprises causing a current to flow between the cathode and an anode plate in an electroplating bath and said-the step (e)(d) comprises ending the current flow.
  - 8. (Cancelled)
- 9. (Currently Amended) A fabrication method of a microlens having a desired radius (R) of curvature, said-the method comprising the steps of:
- (a) preparing a substrate at least a portion of which is electrically conductive;
- (b) forming an insulating mask layer on the conductive portion of the substrate such that the insulating mask layer has an opening to expose the conductive portion of the substrate, a diameter or width  $(\phi)$  of the opening being  $10\mu\text{m} \le \phi \le 0.35R$  and  $R \le 200\mu\text{m}$ ;

(c) forming an opening in the mask layer to expose the conductive portion of the substrate at the opening such that a diameter or width  $(\phi)$  of the opening is  $10\mu\text{m} \le \phi \le 0.35\text{R}$  and  $R \le 200\mu\text{m}$ ;

(d) performing electroplating using the conductive portion of the substrate as a cathode to deposit a plated <u>layer portion</u> in the opening and on the mask layer;

 $\label{eq:continuous} \frac{\text{(e)}(d)}{(d)} \text{ terminating electroplating when the plated } \frac{\text{layer-portion}}{\text{portion}} \text{ reaches the}$  desired radius (R) of curvature after forming a minimum radius (R\_min) of curvature;

- (e) forming a sacrificial layer on the plated portion;
- (f) forming an electrode layer on the sacrificial layer;
- (g) forming a plated portion used as the mold on the electrode layer by electroplating by using the electrode layer as a cathode(f) forming a mold on the substrate;

(g)(h) separating the mold from the substrate by etching the sacrificial layer;

(h)(i) coating forming a lens material on the mold; and

(i)(i) separating the lens material from the mold,

wherein the desired radius (R) of curvature and the minimum radius  $(R_{min})$  are radii at an optical axis of the plated portion.